

IN THE CLAIMS:

Please amend Claim 5 and add new Claim 12, as shown below.

1 to 4. (Cancelled)

5. (Currently Amended) An image pickup apparatus comprising:
a lead of a flexible wiring film;
an image pickup element chip electrically connected to the lead at an
electrical connection point; and
a cover glass for protecting a surface of the image pickup element chip,
wherein the lead, the image pickup element chip, and the cover glass are
sealed with a sealant in a peripheral portion of the image pickup element chip,
wherein the lead has a hole formed in a portion of the lead in contact with
the sealant, the portion of the lead being between the electrical connection point and an
area outer end of the lead bonded to an insulating base film, and
wherein a part of the hole is positioned outside the cover glass, and
wherein the lead has a thickness of not greater than 35 µm.

6 and 7. (Cancelled)

8. (Previously Presented) The image pickup apparatus according to Claim
5, wherein at least one of a layer for preventing reflection of external light and a layer for
preventing multiple reflection is formed between the lead and the cover glass.

9. (Previously Presented) An image pickup system comprising:
the image pickup apparatus according to Claim 5;
an optical system for focusing light on the image pickup apparatus; and
a signal processing circuit for processing an output signal from the image
pickup apparatus.

10 and 11. (Cancelled)

12. (New) The image pickup apparatus according to Claim 5, wherein the
thickness of the lead is within the range of 18 μm to 35 μm .